



Material Content Data Sheet



Sales Product Name		BTS436L2G		Issued		13. April 2015		
MA#		MA001120908						
Package		PG-TO263-5-2		Weight*		1546.56 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.066	0.33	0.33	3276	3276
leadframe	non noble metal	iron	7439-89-6	0.790	0.05		511	
	inorganic material	phosphorus	7723-14-0	0.237	0.02		153	
	non noble metal	copper	7440-50-8	788.527	50.97	51.04	509860	510524
wire	non noble metal	aluminium	7429-90-5	3.486	0.23	0.23	2254	2254
encapsulation	organic material	carbon black	1333-86-4	1.245	0.08		805	
	plastics	epoxy resin	-	57.279	3.70		37036	
	inorganic material	silicondioxide	60676-86-0	564.073	36.47	40.25	364729	402570
leadfinish	non noble metal	tin	7440-31-5	10.339	0.67	0.67	6685	6685
plating	inorganic material	phosphorus	7723-14-0	0.008	0.00		5	
	non noble metal	nickel	7440-02-0	3.422	0.22	0.22	2212	2217
solder	noble metal	silver	7440-22-4	0.100	0.01		65	
	non noble metal	tin	7440-31-5	0.080	0.01		52	
	non noble metal	lead	7439-92-1	3.820	0.25	0.27	2470	2587
heatspreader	non noble metal	iron	7439-89-6	0.108	0.01		70	
	inorganic material	phosphorus	7723-14-0	0.032	0.00		21	
	non noble metal	copper	7440-50-8	107.943	6.98	6.99	69796	69887
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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